

# KJLC 150LX Atomic Layer Deposition

## Overview

The Kurt J. Lesker Company® (KJLC®) ALD150LX™ is an Atomic Layer Deposition (ALD) system designed specifically for advanced research and development (R&D) applications. Innovative ALD150LX™ design features, like our Patented Precursor Focusing Technology™, blended with advanced process capability provide unparalleled flexibility and performance. With an emphasis on enabling and supporting innovative, cutting edge technology at the R&D level, the ALD150LX™ serves not only as a stand-alone platform, but provides connectivity with additional process and analysis modules in a cluster tool configuration.

LMACS Name	ALD - KJLC 150LX
Confluence Label	<a href="#">kjlc-150lx-ald</a>
Process Area	DEPOSITION
Model	<a href="#">ALD 150LX</a>
Vendor	Kurt J. Lesker (KJL)
Team	Aaron Hryciw Scott Munro Devin Fortier

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## System Features

Substrate Handling	Load locked single wafer transfer  Substrate sizes:  <table border="1"><thead><tr><th>min</th><th>max</th><th>thickness</th></tr></thead><tbody><tr><td>2 mm x 2 mm</td><td>150 mm ø</td><td>5 mm thickness w/o carrier 3 mm with carrier</td></tr></tbody></table>	min	max	thickness	2 mm x 2 mm	150 mm ø	5 mm thickness w/o carrier 3 mm with carrier
min	max	thickness					
2 mm x 2 mm	150 mm ø	5 mm thickness w/o carrier 3 mm with carrier					
Substrate Heating	up to 500 °C						
Sources	Source 1 - Single Vapour Draw (H <sub>2</sub> O)  Source 2 - Flow through  Source 3 - Multi-source Vapour Draw (5 ampoules)  Source 4 - Flow-through heated oven						
Materials	<ul style="list-style-type: none"><li>• Aluminium oxide (Al<sub>2</sub>O<sub>3</sub>)<ul style="list-style-type: none"><li>◦ TMA + H<sub>2</sub>O</li><li>◦ TMA + O<sub>2</sub> plasma</li><li>◦ TMA + O<sub>3</sub></li></ul></li><li>• Silicon dioxide (SiO<sub>2</sub>)<ul style="list-style-type: none"><li>◦ 3DMAS + O<sub>2</sub> plasma</li></ul></li><li>• Hafnium oxide (HfO<sub>2</sub>)<ul style="list-style-type: none"><li>◦ TDMAH + H<sub>2</sub>O</li><li>◦ TDMAH + O<sub>2</sub> plasma</li></ul></li><li>• Zirconium oxide (ZrO<sub>2</sub>)<ul style="list-style-type: none"><li>◦ TDMAZ + H<sub>2</sub>O</li><li>◦ TDMAZ + O<sub>2</sub> plasma</li></ul></li><li>• Silicon nitride (Si<sub>3</sub>N<sub>4</sub>)<ul style="list-style-type: none"><li>◦ 3DMAS + N<sub>2</sub> plasma</li></ul></li><li>• Titanium nitride (TiN)<ul style="list-style-type: none"><li>◦ TiCl<sub>4</sub> + N<sub>2</sub>/H<sub>2</sub> plasma</li></ul></li><li>• Aluminum nitride (AlN)<ul style="list-style-type: none"><li>◦ TMA + N<sub>2</sub> plasma</li></ul></li></ul>						

<b>Plasma Source Gases</b>	Source 5 - 1 kW RF Remote ICP <ul style="list-style-type: none"><li>• Argon (Ar)</li><li>• Oxygen (O<sub>2</sub>)</li><li>• Nitrogen (N<sub>2</sub>)</li><li>• Hydrogen (H<sub>2</sub>)</li><li>• Ammonia (NH<sub>3</sub>)</li><li>• Ozone (O<sub>3</sub>) - via ozone generator (non-plasma)</li></ul>
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## Process Information

Please see the [KJLC ALD 150LX process information](#) page for a listing of qualified recipes and associated data.

## Documents

<b>Operating Procedure</b>	<a href="#">KJLC 150LX ALD SOP</a>
<b>Hazard Assessment</b>	<a href="#">KJLC 150LX ALD Hazard Assessment</a>

## Related Documents

- [KJLC 150LX Atomic Layer Deposition \(Equipment\)](#)
  - [equipment](#)
  - [requires-update](#)
  - [kjl-150lx-ald](#)
  - [\\$labeltext](#)
  - [deposition](#)